700V N-CHANNEL ENHANCEMENT MODE MOSFET

Product Summary

$V_{(BR)DSS}$	$R_{DS(on)\ max}$	I_D T_C = +25°C
700V	1.25Ω @ V_{GS} = 10V	3.9A

Description

This new generation MOSFET has been designed to minimize the on-state resistance ($R_{DS(on)}$) and yet maintain superior switching performance, making it ideal for high efficiency power management applications.

Applications

- Switching

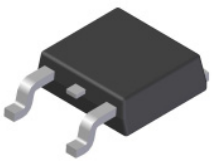
Features

- 100% Unclamped Inductive Switch (UIS) test in production
- Low Gate Input Resistance
- Low Input Capacitance
- **Lead-Free Finish; RoHS Compliant (Notes 1 & 2)**
- **Halogen and Antimony Free. "Green" Device (Note 3)**
- **Qualified to AEC-Q101 Standards for High Reliability**

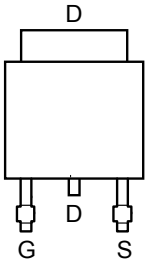
Mechanical Data

- Case: TO252 (DPAK)
- Case Material: Molded Plastic, "Green" Molding Compound. UL Flammability Classification Rating 94V-0
- Moisture Sensitivity: Level 1 per J-STD-020
- Terminal Connections: See Diagram
- Terminals: Finish – Matte Tin annealed over Copper leadframe. Solderable per MIL-STD-202, Method 208 e3
- Weight: 0.33 grams (approximate)

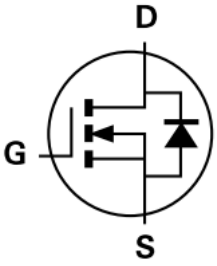
TO252



Top View



Top View



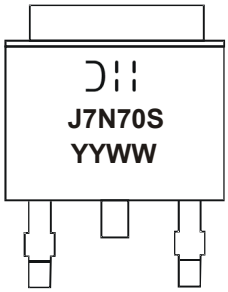
Internal Schematic

Ordering Information (Note 4)

Part Number	Compliance	Case	Packaging
DMJ7N70SK3-13	Standard	TO252	2,500/Tape & Reel

Notes:
1. EU Directive 2002/95/EC (RoHS) & 2011/65/EU (RoHS 2) compliant. All applicable RoHS exemptions applied.
2. See http://www.diodes.com/quality/lead_free.html for more information about Diodes Incorporated's definitions of Halogen- and Antimony-free, "Green" and Lead-free.
3. Halogen- and Antimony-free "Green" products are defined as those which contain <900ppm bromine, <900ppm chlorine (<1500ppm total Br + Cl) and <1000ppm antimony compounds.
4. For packaging details, go to our website at http://www.diodes.com/products/packages.html.

Marking Information



=Manufacturer's Marking
J7N70S = Product Type Marking Code
YYWW = Date Code Marking
YY = Last Digit of Year (ex: 13 = 2013)
WW = Week Code (01 to 53)

Maximum Ratings (@T_A = +25°C, unless otherwise specified.)

Characteristic		Symbol	Value	Units
Drain-Source Voltage		V_{DSS}	700	V
Gate-Source Voltage		V_{GSS}	±30	V
Continuous Drain Current (Note 5) V_{GS} = 10V	T_C = +25°C T_C = +100°C	I_D	3.9 2.5	A
Maximum Body Diode Forward Current (Note 5)		I_S	3.0	A
Pulsed Drain Current (10µs pulse, duty cycle = 1%)		I_{DM}	15.6	A
Avalanche Current (Note 6)		I_{AR}	1.5	A
Avalanche Energy (Note 6)		E_{AR}	76	mJ
Peak Diode Recovery dv/dt		dv/dt	11.8	V/ns

Thermal Characteristics (@T_A = +25°C, unless otherwise specified.)

Characteristic		Symbol	Value	Units
Total Power Dissipation (Note 5)	T_C = +25°C	P_D	28	W
	T_C = +100°C		11	
Thermal Resistance, Junction to Ambient (Note 5)		$R_{\theta JA}$	38	°C/W
Thermal Resistance, Junction to Case (Note 5)		$R_{\theta JC}$	2.1	
Operating and Storage Temperature Range		T_J, T_{STG}	-55 to +150	°C

Electrical Characteristics (@T_A = +25°C, unless otherwise specified.)

Characteristic	Symbol	Min	Typ	Max	Unit	Test Condition
OFF CHARACTERISTICS (Note 7)						
Drain-Source Breakdown Voltage	BV_{DSS}	700	—	—	V	V_{GS} = 0V, I_D = 250µA
Zero Gate Voltage Drain Current	I_{DSS}	—	—	1	µA	V_{DS} = 700V, V_{GS} = 0V
Gate-Source Leakage	I_{GSS}	—	—	100	nA	V_{GS} = ±30V, V_{DS} = 0V
ON CHARACTERISTICS (Note 7)						
Gate Threshold Voltage	$V_{GS(th)}$	2	2.9	4	V	V_{DS} = V_{GS}, I_D = 250µA
Static Drain-Source On-Resistance	$R_{DS(ON)}$	—	1	1.25	Ω	V_{GS} = 10V, I_D = 2.5A
Diode Forward Voltage	V_{SD}	—	0.9	1.3	V	V_{GS} = 0V, I_S = 5A
DYNAMIC CHARACTERISTICS (Note 8)						
Input Capacitance	C_{iss}	—	351	—	pF	V_{DS} = 50V, f = 1MHz, V_{GS} = 0V
Output Capacitance	C_{oss}	—	66	—		
Reverse Transfer Capacitance	C_{rss}	—	1.1	—		
Gate Resistance	R_G	—	3.5	—	Ω	V_{DS} = 0V, V_{GS} = 0V, f = 1MHz
Total Gate Charge	Q_g	—	13.9	—	nC	V_{DD} = 560V, I_D = 5A, V_{GS} = 10V
Gate-Source Charge	Q_{gs}	—	1.9	—		
Gate-Drain Charge	Q_{gd}	—	8.5	—		
Turn-On Delay Time	$t_{D(on)}$	—	8.5	—	ns	V_{DD} = 350V, V_{GS} = 10V, R_G = 4.7Ω, I_D = 2.5A
Turn-On Rise Time	t_r	—	11.6	—		
Turn-Off Delay Time	$t_{D(off)}$	—	24.5	—		
Turn-Off Fall Time	t_f	—	10	—		
Body Diode Reverse Recovery Time	t_{rr}	—	212	—	ns	I_S = 5A, dI/dt = 100A/µs
Body Diode Reverse Recovery Time (T_J = +150°C)	t_{rr}	—	251	—	ns	
Body Diode Reverse Recovery Charge	Q_{rr}	—	1.8	—	µC	
Body Diode Reverse Recovery Charge (T_J = +150°C)	Q_{rr}	—	2.3	—	µC	

Notes:
5. Device mounted on FR-4 substrate PC board, 2oz copper, with 1inch square copper pad layout.
6. UIS in production with V_{DD} = 50V, V_{GS} = 10V, L = 60mH, T_J = +25°C.
7. Short duration pulse test used to minimize self-heating effect
8. Guaranteed by design. Not subject to production testing

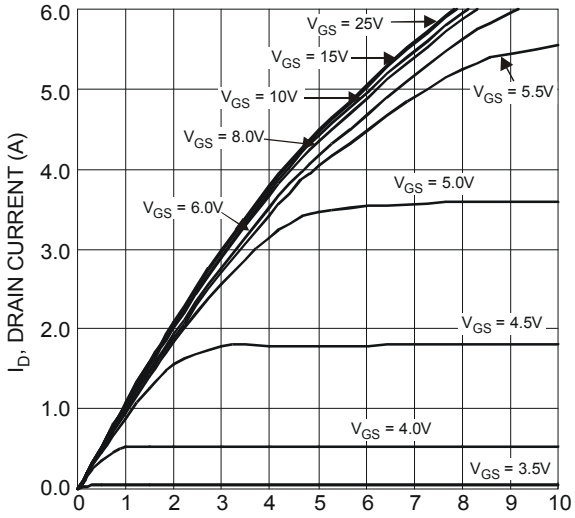


Figure 1 Typical Output Characteristics

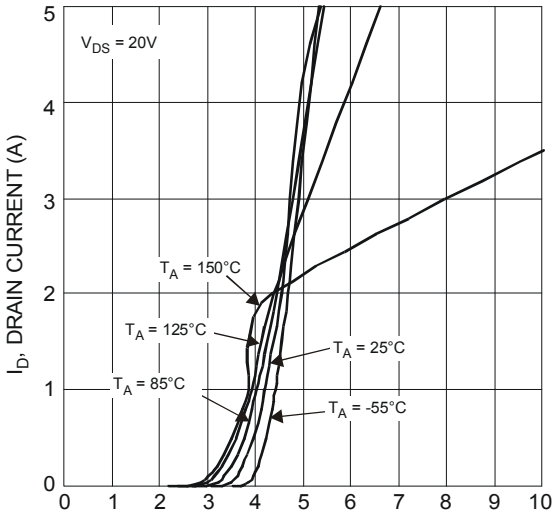


Figure 2 Typical Transfer Characteristics

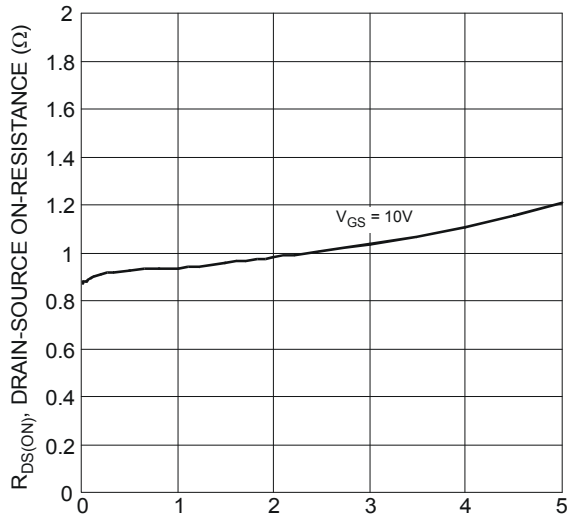


Figure 3 Typical On-Resistance vs. Drain Current and Gate Voltage

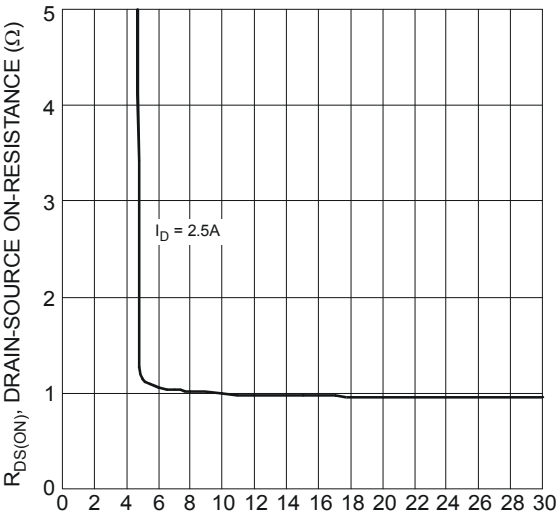


Figure 4 Typical Transfer Characteristics

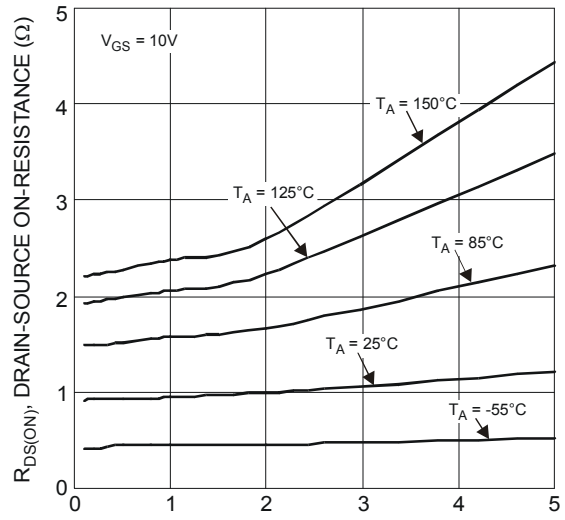


Figure 5 Typical On-Resistance vs. Drain Current and Temperature

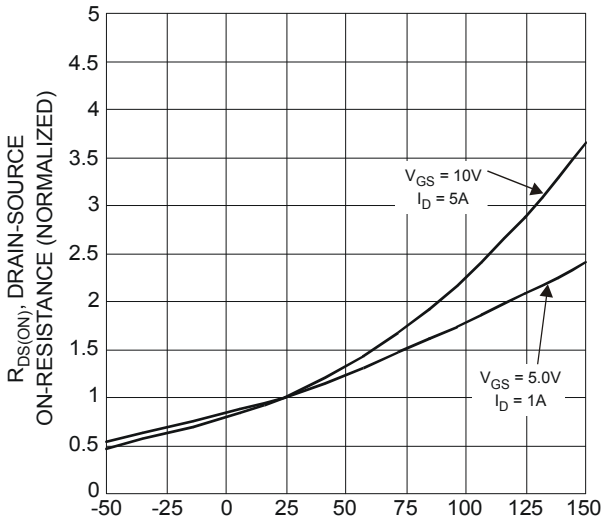


Figure 6 On-Resistance Variation with Temperature

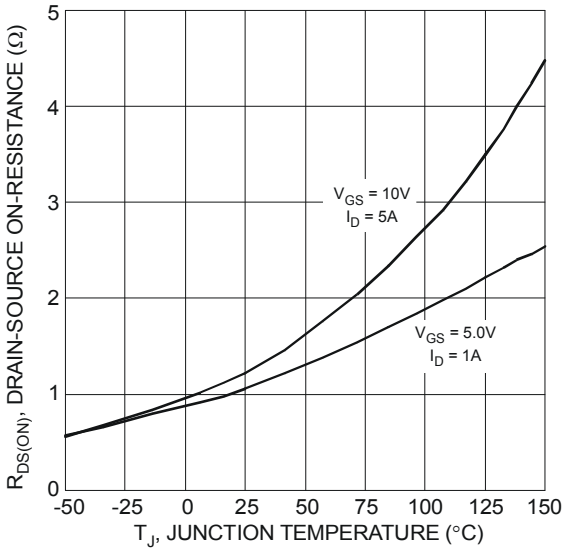


Figure 7 On-Resistance Variation with Temperature

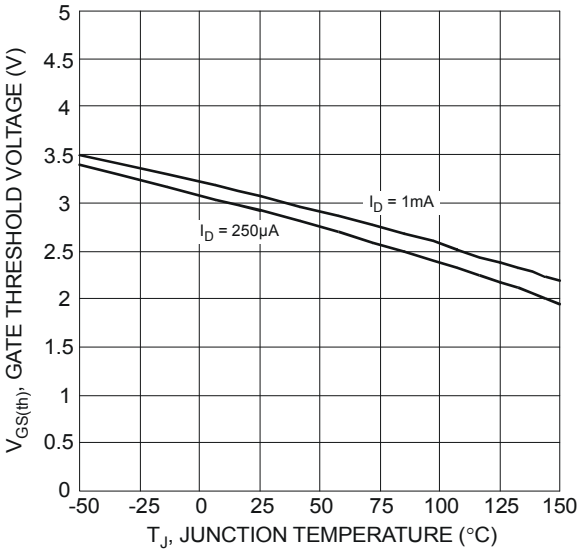


Figure 8 Gate Threshold Variation vs. Ambient Temperature

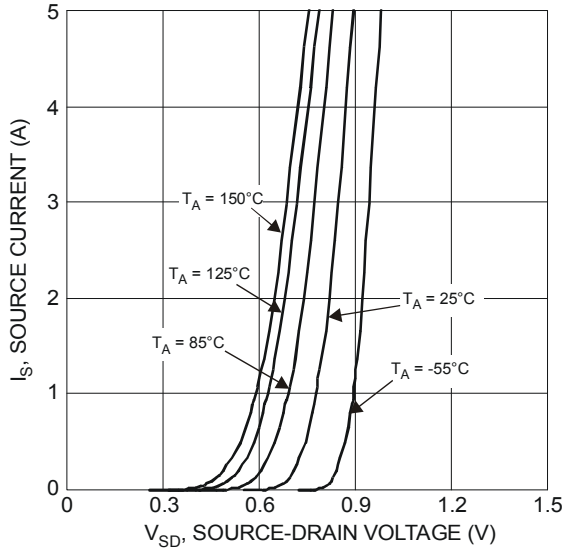


Figure 9 Diode Forward Voltage vs. Current

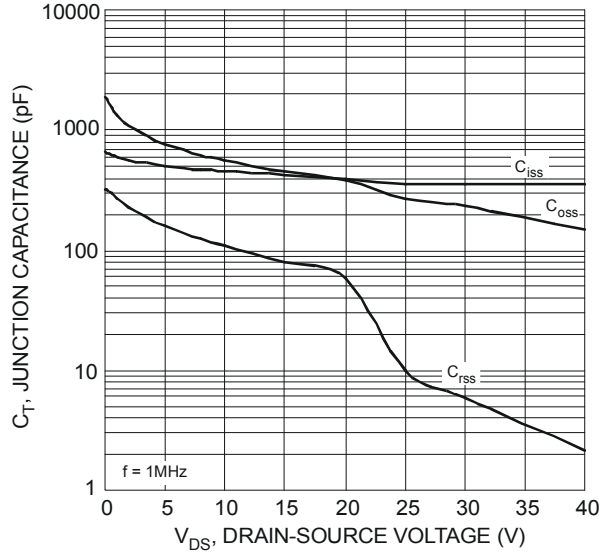


Figure 10 Typical Junction Capacitance

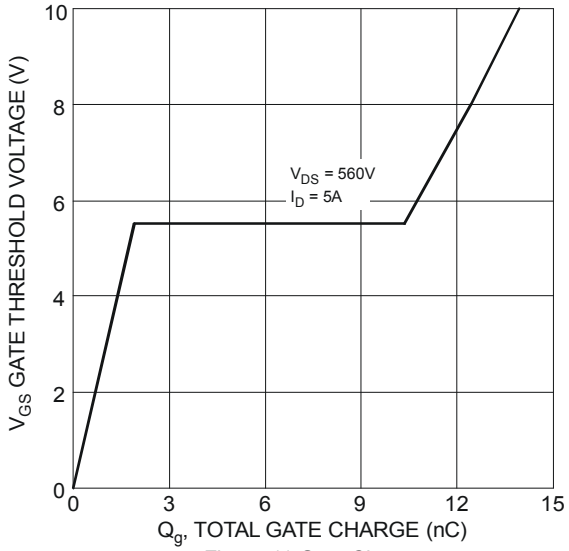


Figure 11 Gate Charge

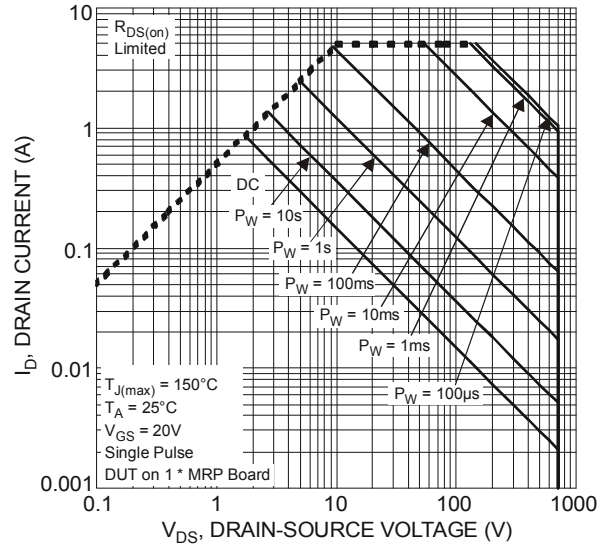


Figure 12 SOA, Safe Operation Area

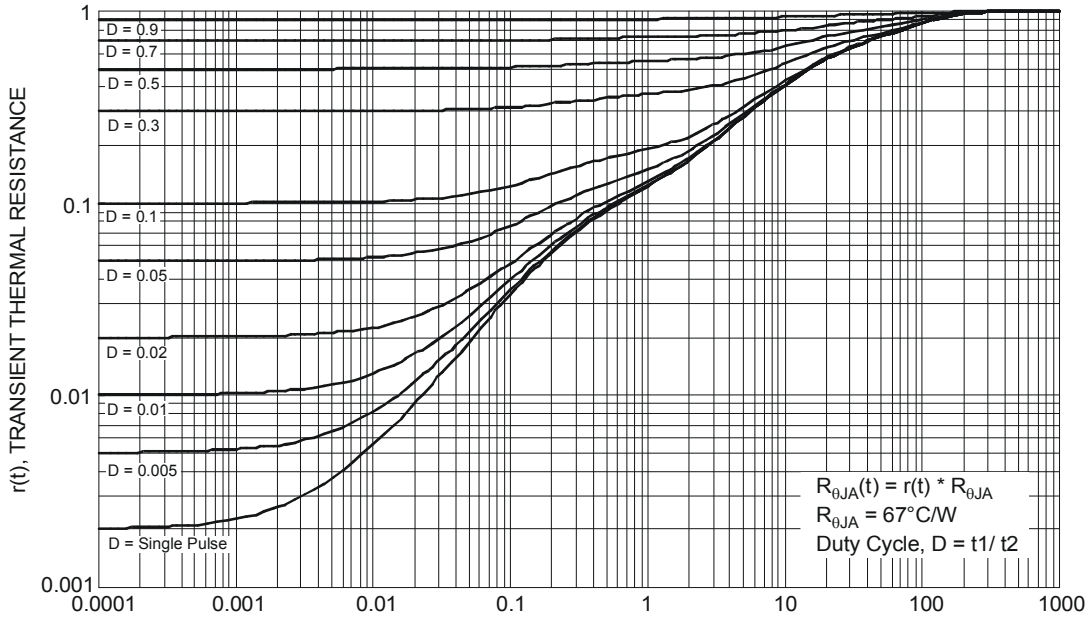
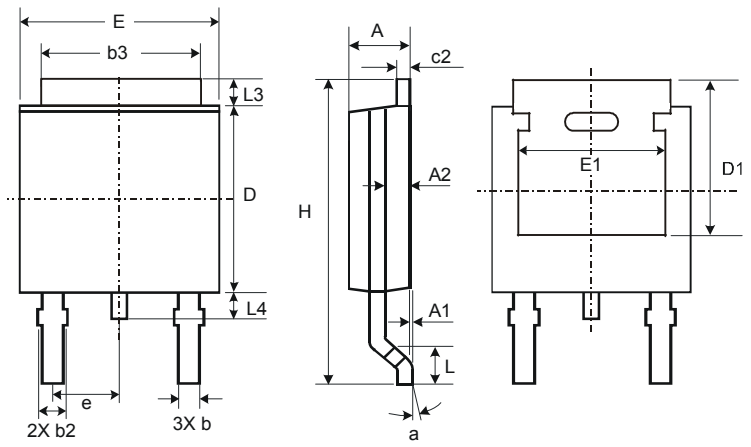


Figure 13 Transient Thermal Resistance

Package Outline Dimensions

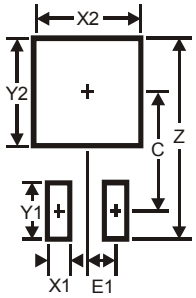
Please see AP02002 at http://www.diodes.com/datasheets/ap02002.pdf for latest version.



TO252			
Dim	Min	Max	Typ
A	2.19	2.39	2.29
A1	0.00	0.13	0.08
A2	0.97	1.17	1.07
b	0.64	0.88	0.783
b2	0.76	1.14	0.95
b3	5.21	5.46	5.33
c2	0.45	0.58	0.531
D	6.00	6.20	6.10
D1	5.21	–	–
e	–	–	2.286
E	6.45	6.70	6.58
E1	4.32	–	–
H	9.40	10.41	9.91
L	1.40	1.78	1.59
L3	0.88	1.27	1.08
L4	0.64	1.02	0.83
a	0°	10°	–
All Dimensions in mm			

Suggested Pad Layout

Please see AP02001 at http://www.diodes.com/datasheets/ap02001.pdf for the latest version.



Dimensions	Value (in mm)
Z	11.6
X1	1.5
X2	7.0
Y1	2.5
Y2	7.0
C	6.9
E1	2.3

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